

Versal: The New Xilinx Adaptive Compute Acceleration Platform (ACAP) in 7nm

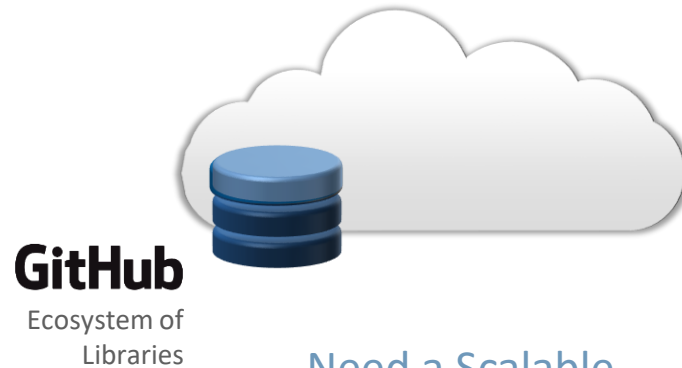
Presented By

Kees Vissers
Fellow

July 11, 2019
MPSoC 2019



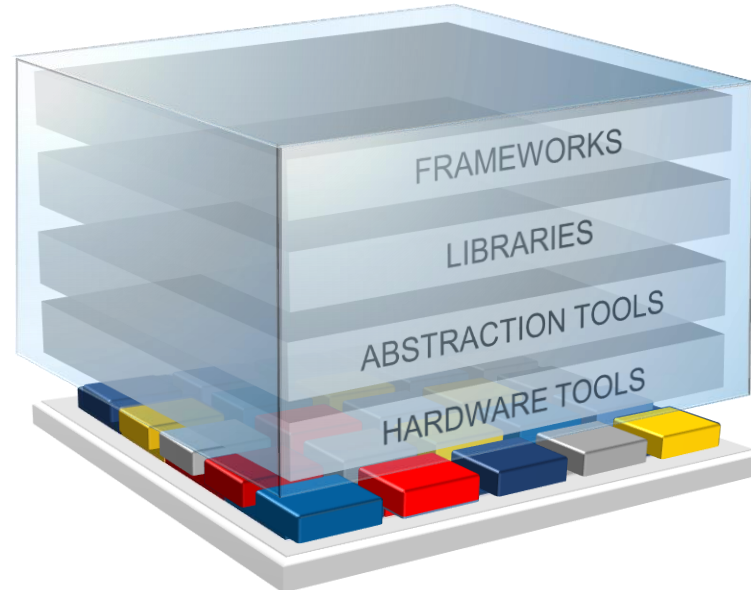
Need for a New Programming Paradigm



Software Developer
Needs Agility and Abstraction



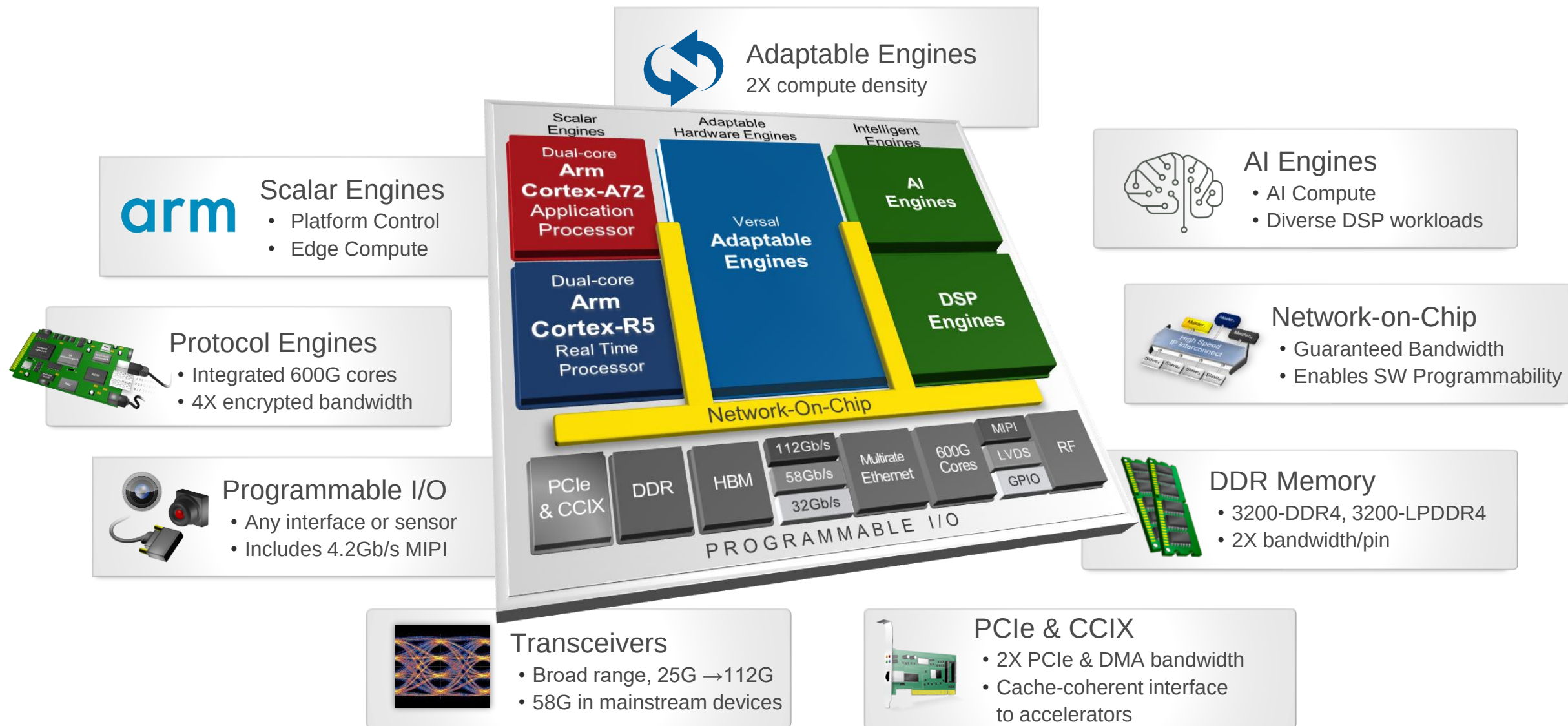
**Need a Scalable,
Unified Platform**



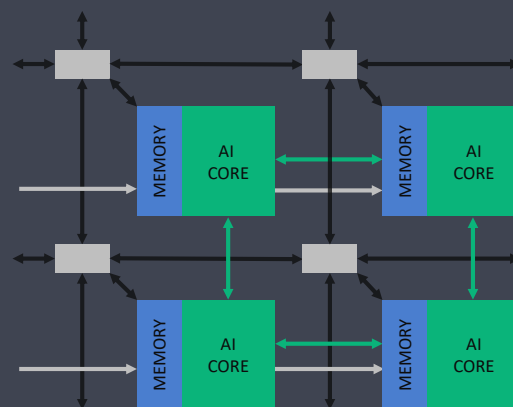
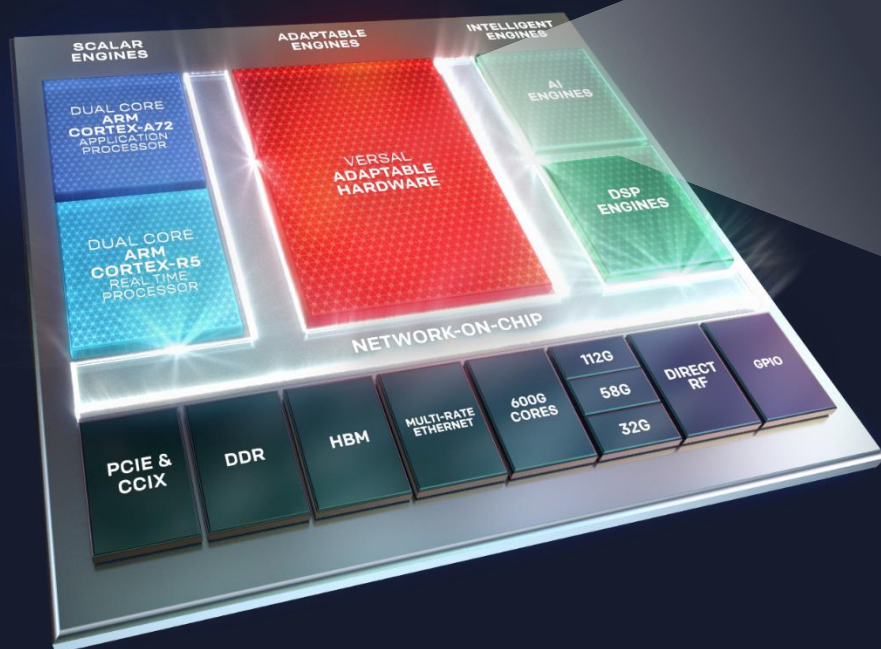
Hardware Developer
Needs Flexibility to Optimize for Performance/Power



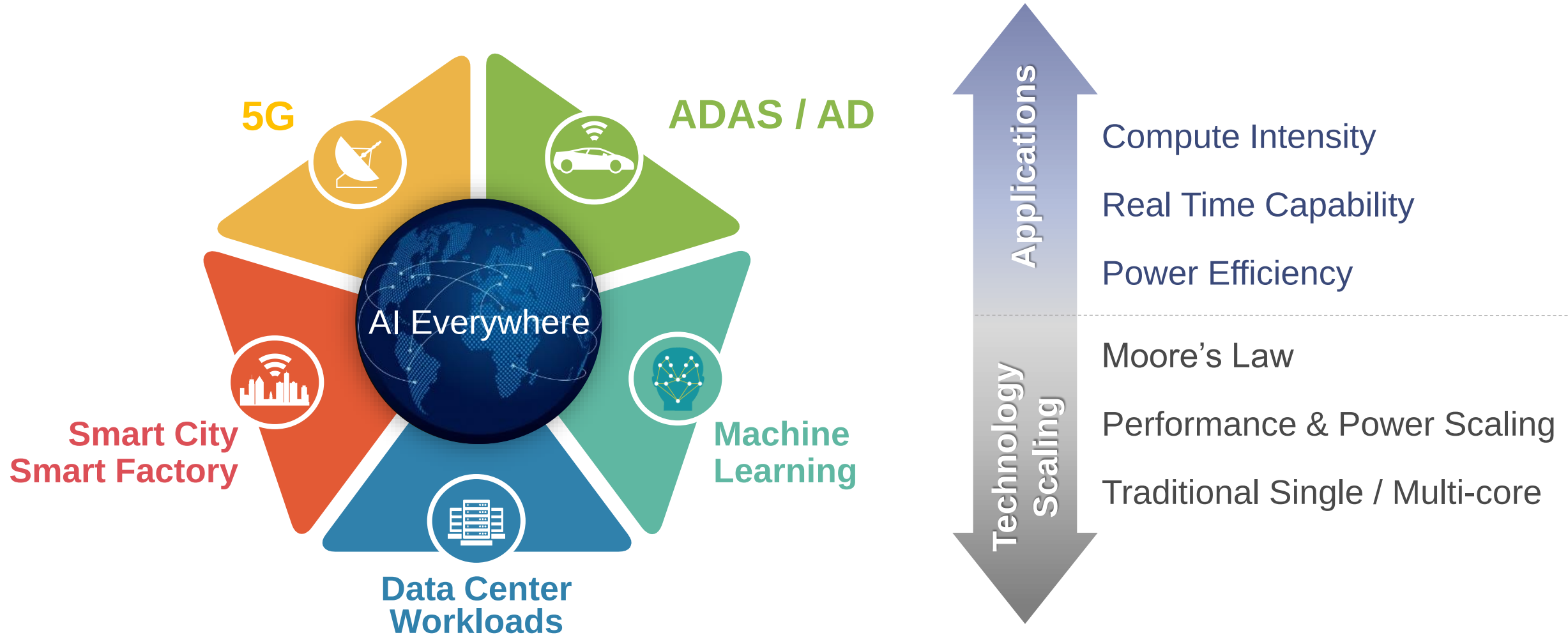
Versal Architecture Overview



Motivation for AI Engine

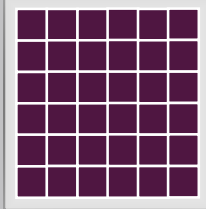
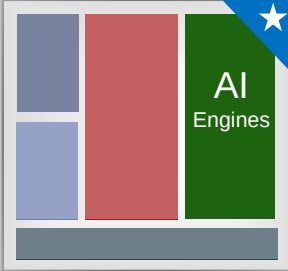
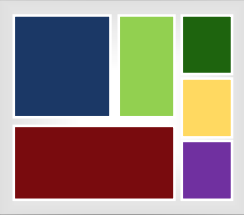


Motivation for AI Engine



Dynamic Markets Require Adaptable Compute Acceleration

Delivering Adaptable Compute Acceleration

	CPU (Sequential)  GPU (Parallel) 		ACAP 	Custom ASIC 
SW Programmable	✓	✓	✓	✓
HW Adaptable	—	—	✓	—
Workload Flexibility	✓	✓	✓	—
Throughput vs. Latency	—	—	✓	✓
Device / Power Efficiency	—	—	✓	✓

← ACAP
w/ AI Engine

Software Programmable: Any Developer

1 Design

C/C++

Frameworks

mxnet

TensorFlow

Caffe

4G/5G/Radar
Library

AI
Library

Vision
Library

2 Compile

AI Engine Compiler

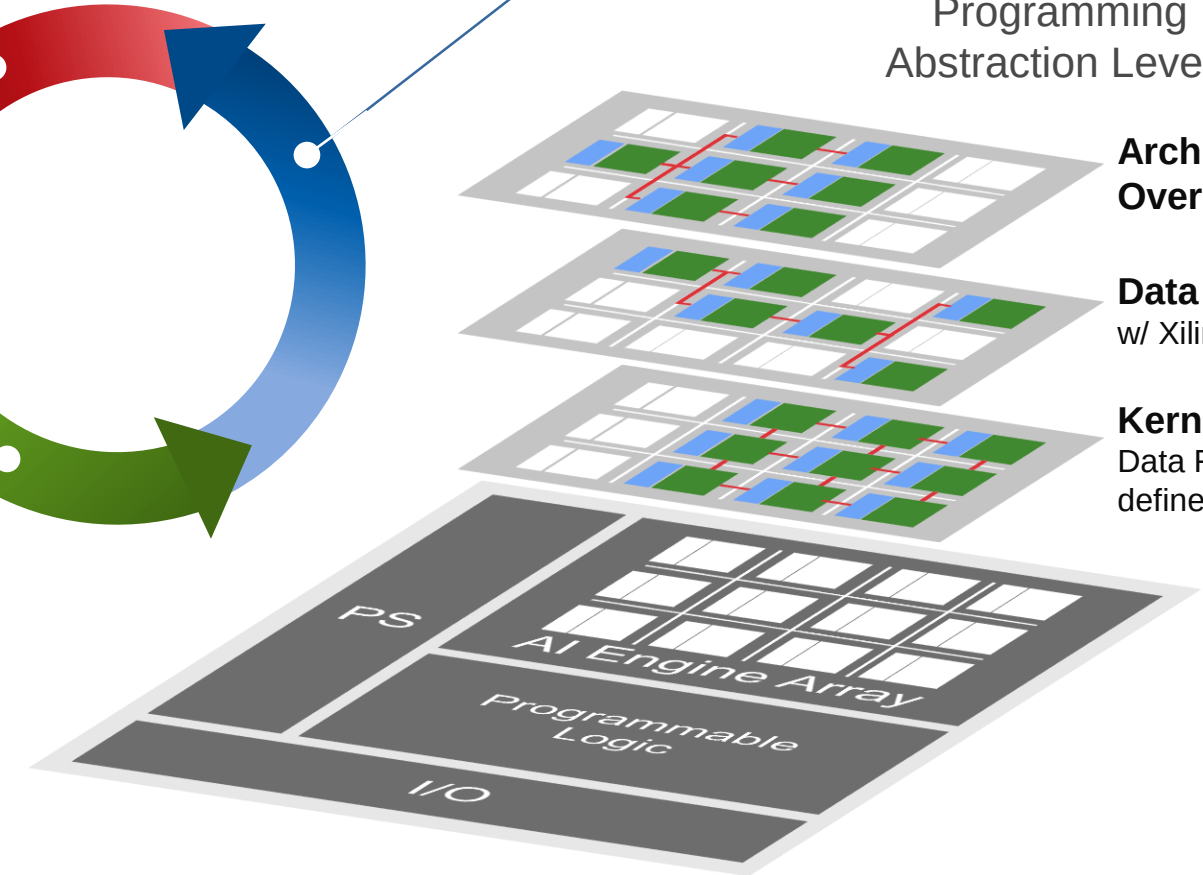
Run 3

Programming
Abstraction Levels

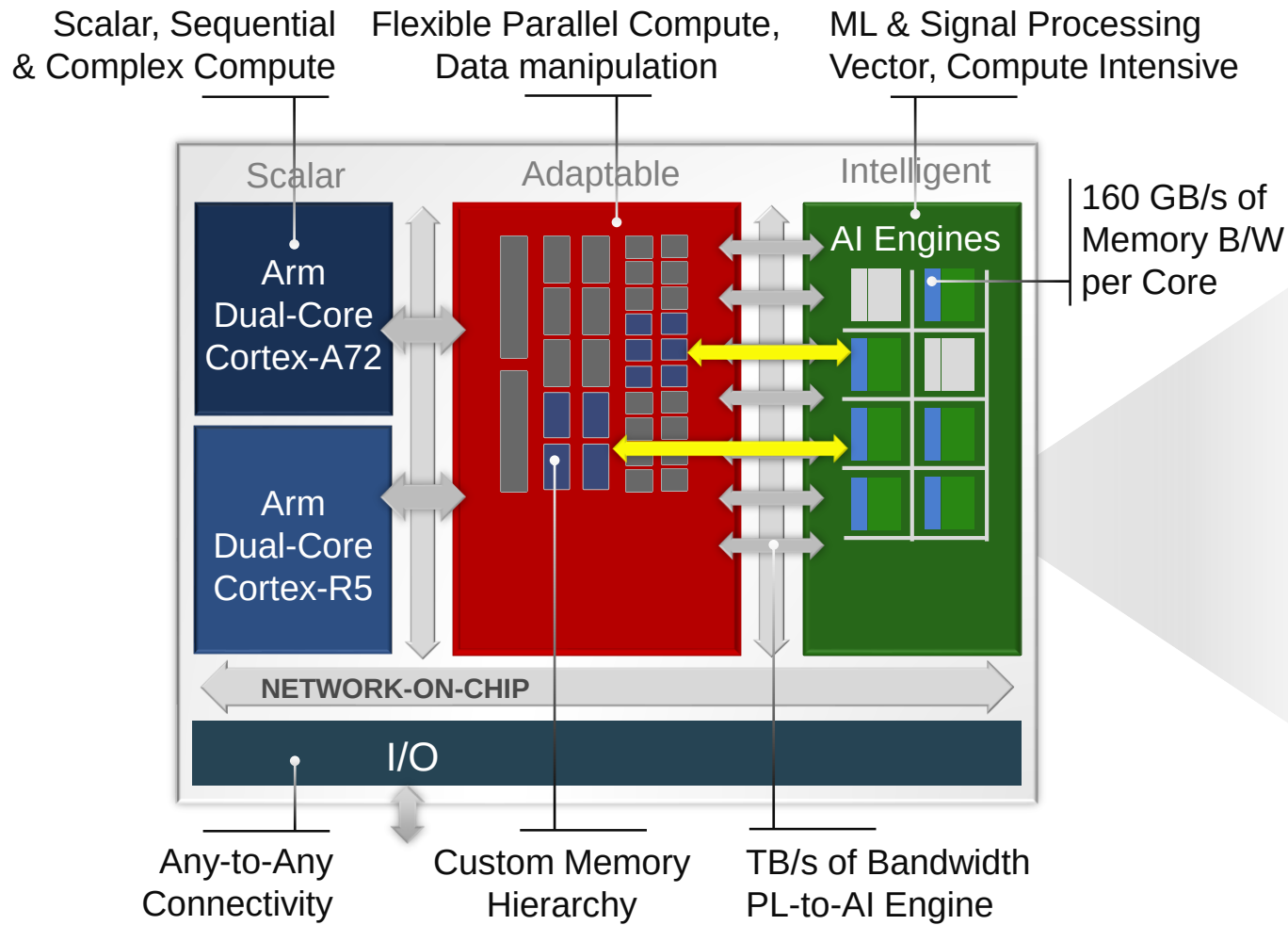
Architecture
Overlay

Data Flow
w/ Xilinx libraries

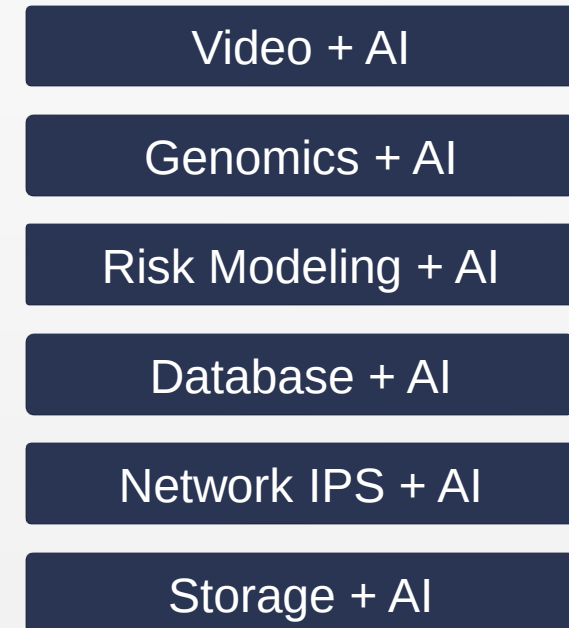
Kernel Program
Data Flow w/ user
defined libraries



Hardware Adaptable: Accelerating the Whole Application

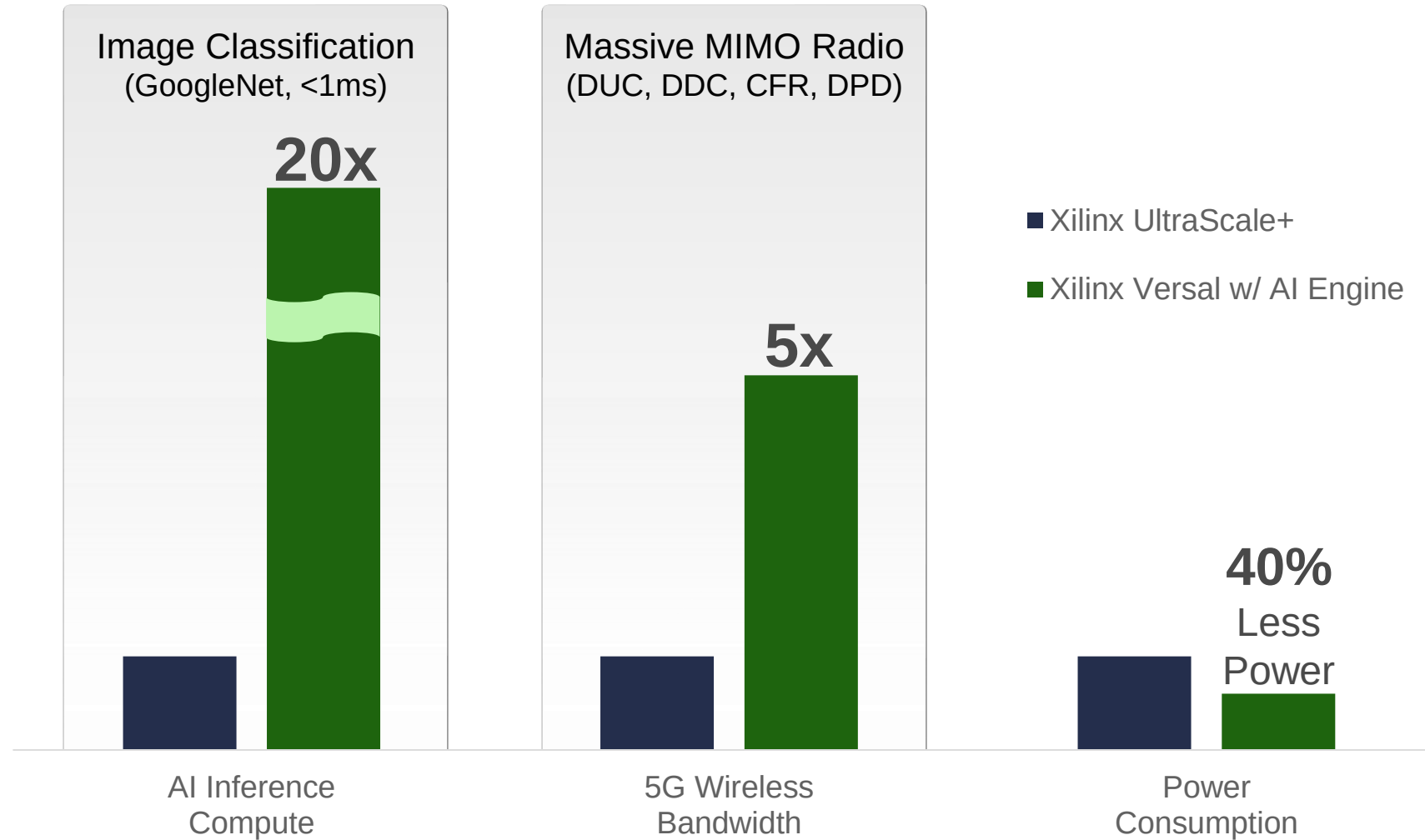


Heterogeneous Acceleration from Data Center to the Edge



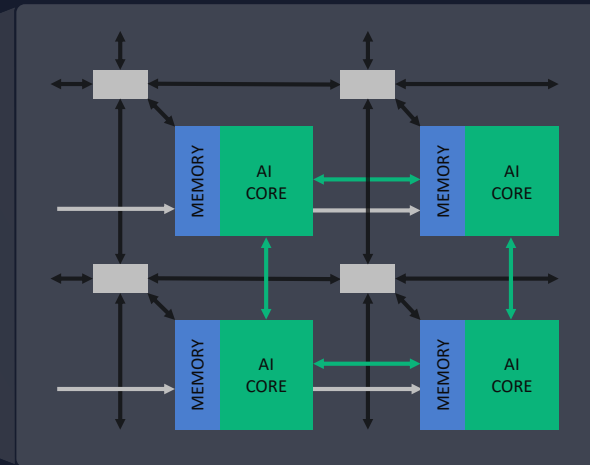
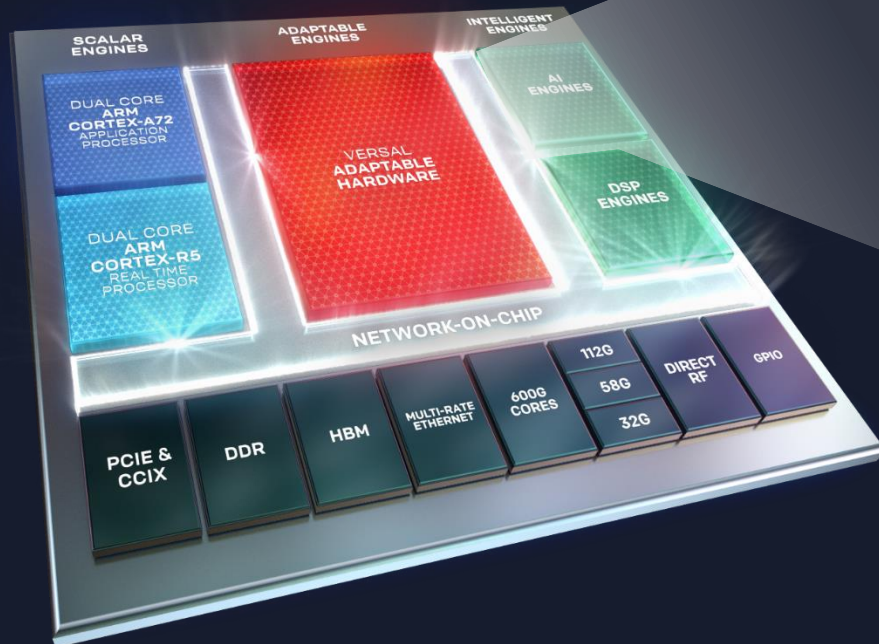
Delivering Deterministic Performance & Low Latency

AI Engine Application Performance & Power Efficiency

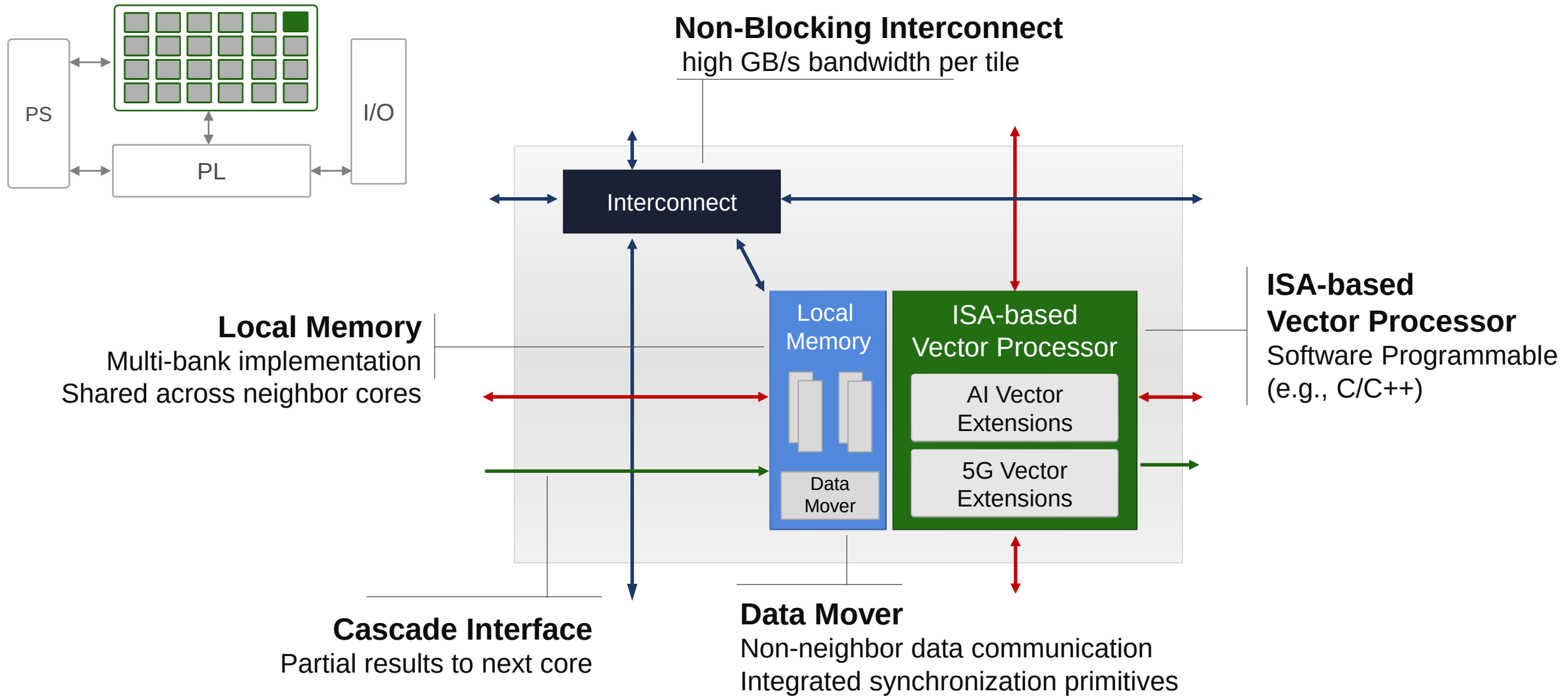


AI Engine

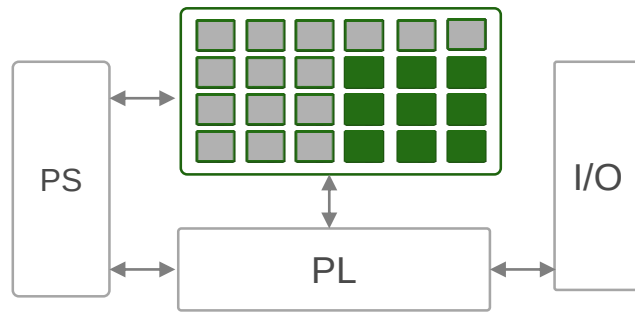
Architecture, Programming & Applications



AI Engine: Tile-Based Architecture



AI Engine: Array Architecture



Modular and scalable architecture

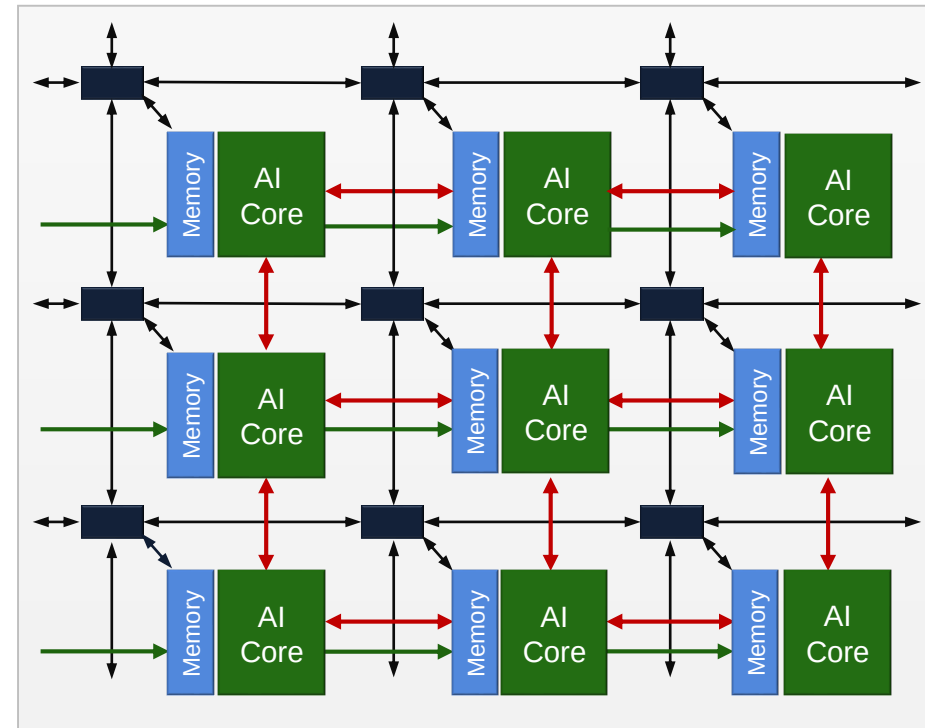
- More tiles = more compute
- Up to 400 per device
 - Versal AI Core VC1902 device

Distributed memory hierarchy

Maximize memory bandwidth

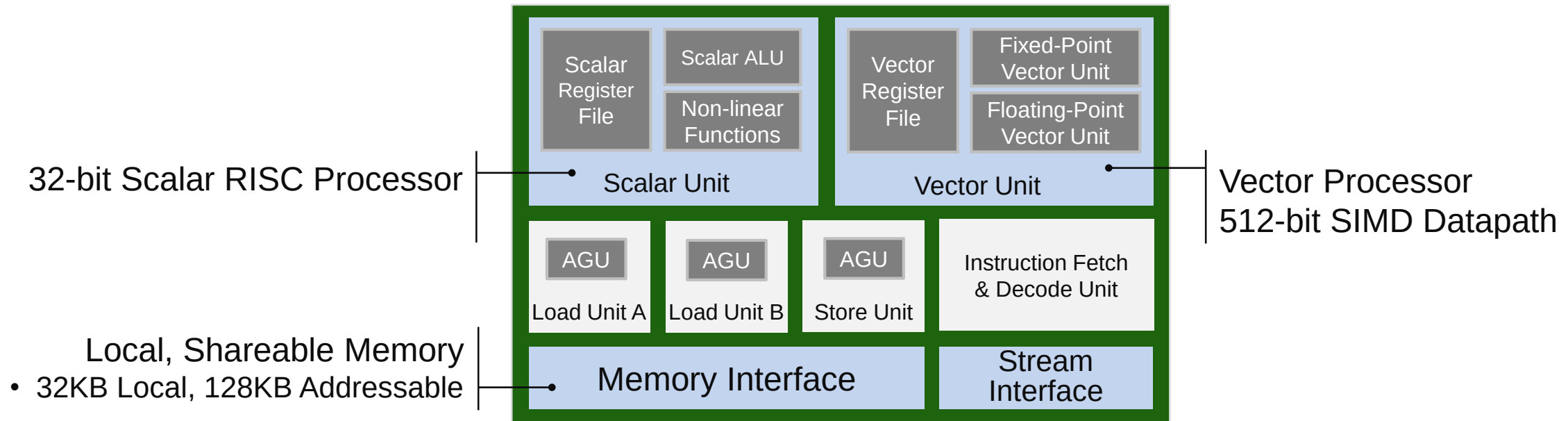
Array of AI Engines

- Increase in compute, memory and communication bandwidth



Deterministic Performance & Low Latency

AI Engine: Processor Core



Instruction Parallelism: VLIW

7+ operations / clock cycle

- 2 Vector Loads / 1 Mult / 1 Store
- 2 Scalar Ops / Stream Access

Highly
Parallel

Data Parallelism: SIMD

Multiple vector lanes

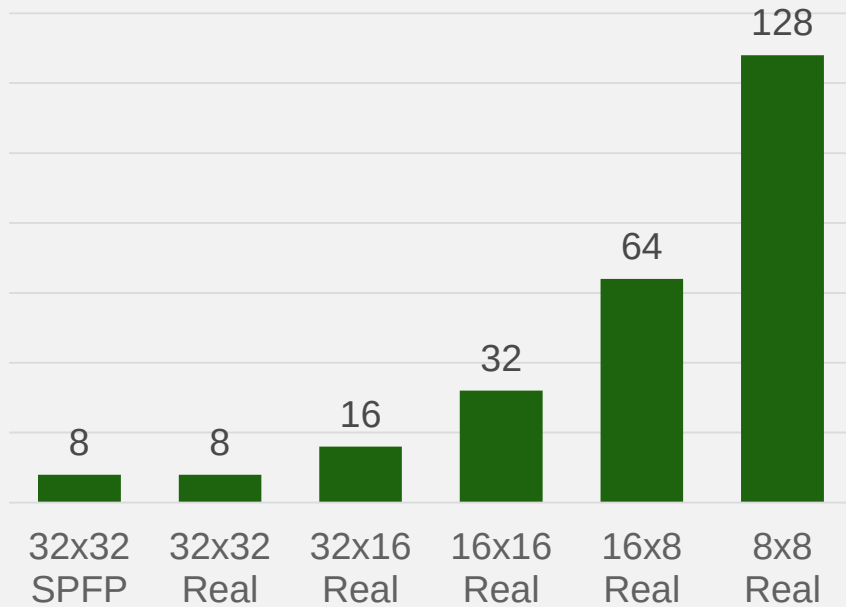
- Vector Datapath
- 8 / 16 / 32-bit & SPFP operands

Up to 128 MACs / Clock Cycle per Core (INT 8)

Multi-Precision Support

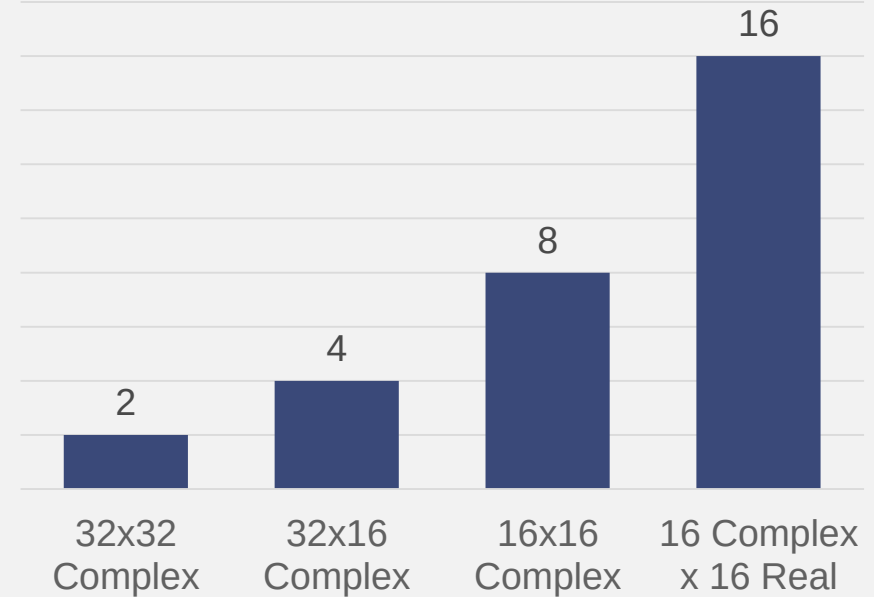
AI Data Types

MACs / Cycle (per core)



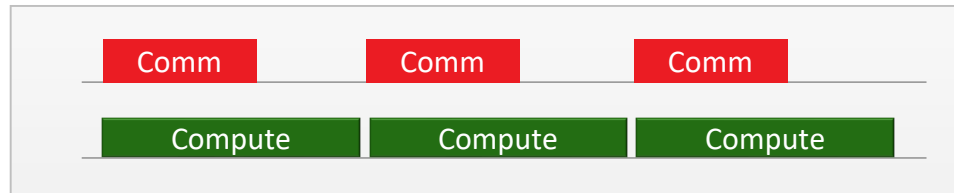
Signal Processing Data Types

MACs / Cycle (per core)



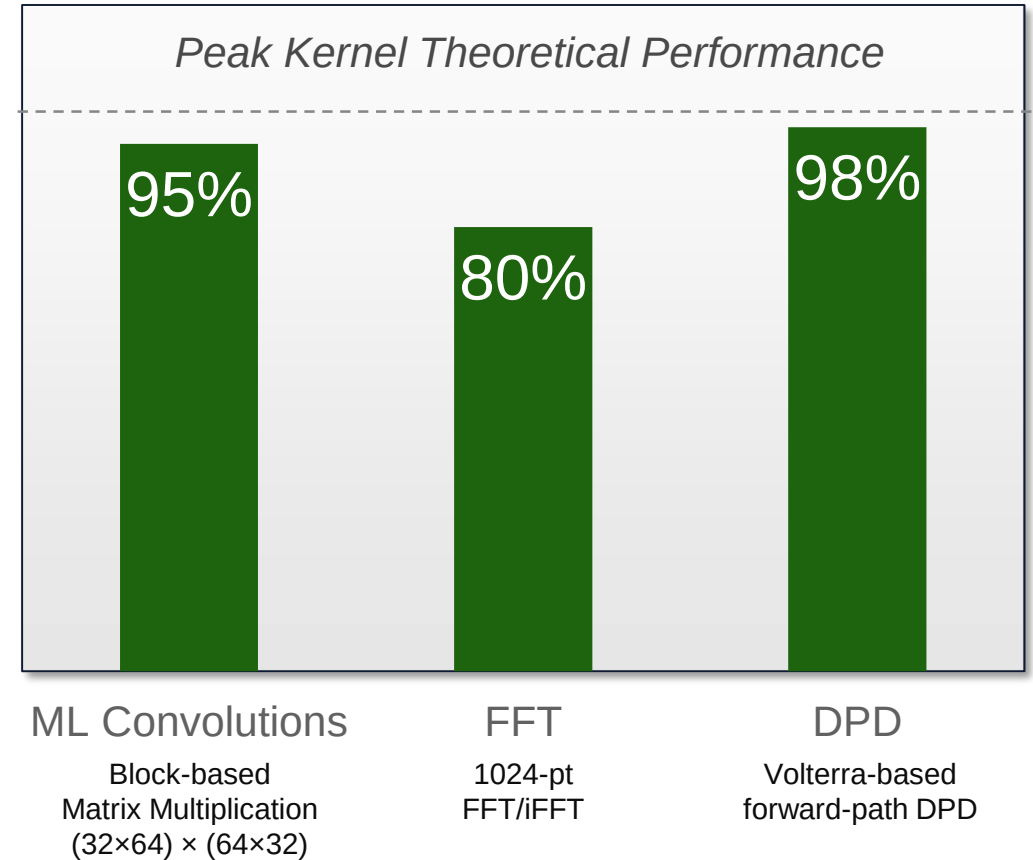
AI Engine Delivers High Compute Efficiency

- > **Adaptable, non-blocking interconnect**
 - >> Flexible data movement architecture
 - >> Avoids interconnect “bottlenecks”
- > **Adaptable memory hierarchy**
 - >> Local, distributed, shareable = extreme bandwidth
 - >> No cache misses or data replication
 - >> Extend to PL memory (BRAM, URAM)
- > **Transfer data while AI Engine Computes**



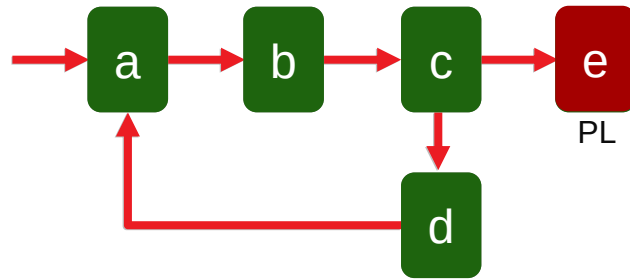
Overlap Compute and Communication

Vector Processor Efficiency



AI Engine Programming Experience: Dataflow Model

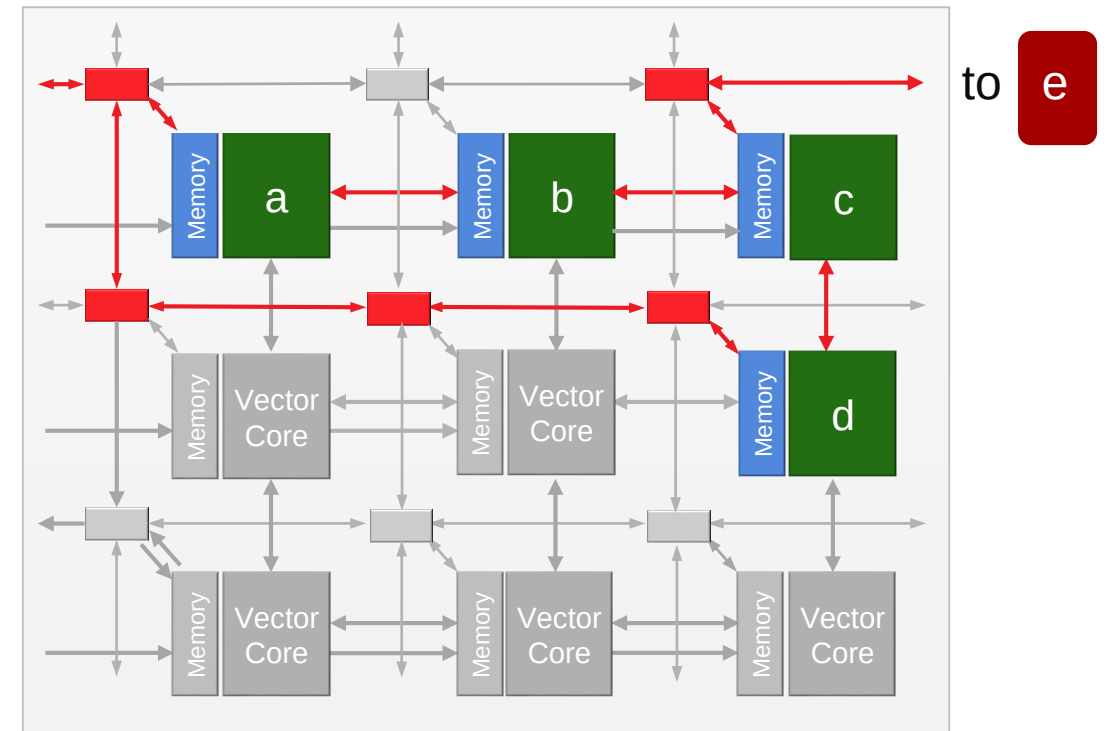
1 User defines dataflow logic



2 User describes dataflow graph using C/C++ APIs

3 Compiler transparently manages placement & interconnect

Physical Mapping to AI Engines



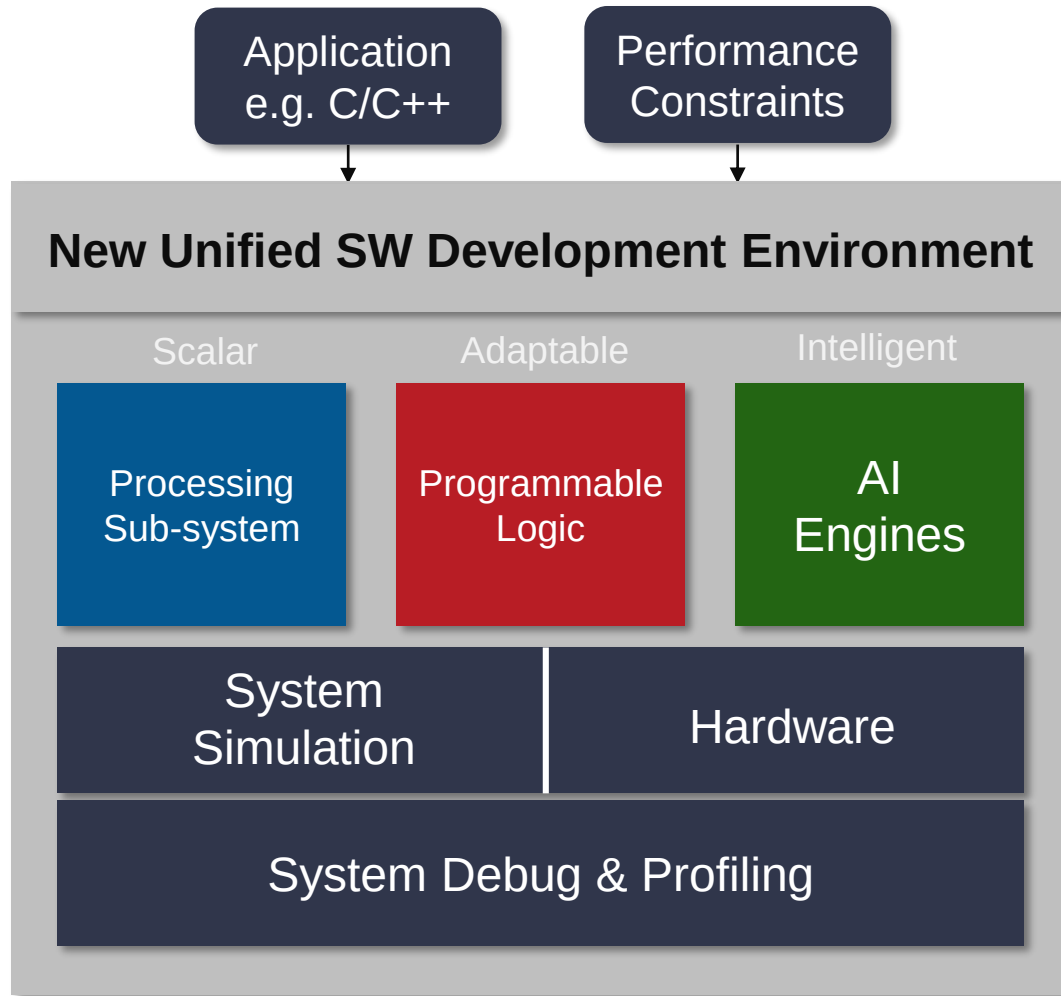
Versal ACAP Development Tools:

TOOLS	USER	SUPPORTED FRAMEWORKS
Frameworks	AI and Data Scientists	Caffe TensorFlow mxnet FFMPEG
New Unified Software Development Environment	Software Application Developers	
Vivado Design Suite	Hardware Developers	



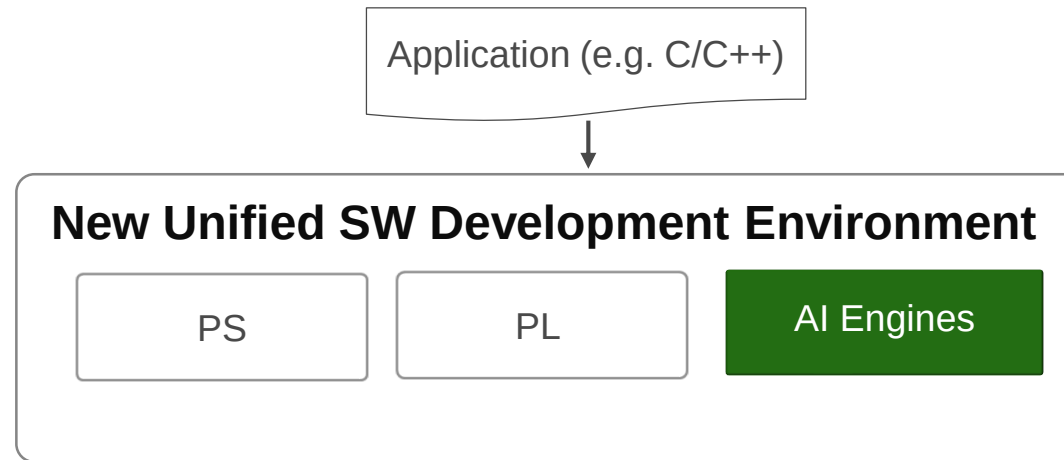
 XILINX. VERSAL™

Software Development Environment

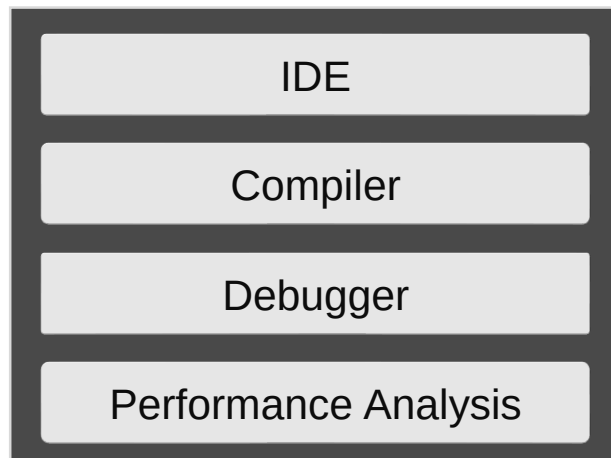


- > **Unified development environment**
 - >> Full chip programming
- > **SW programmable for whole application**
 - >> Heterogeneous SW acceleration
- > **Full system simulation, debug & profiling**
 - >> Software development experience

AI Engine Programming Environment



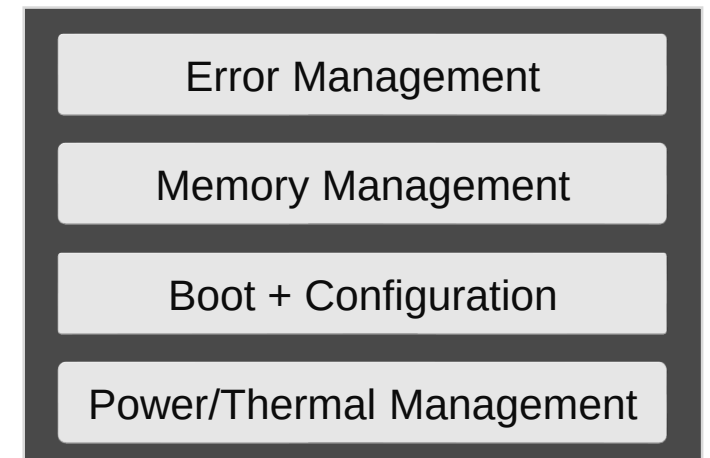
Full SW Programming Tool Chain (Single-engine and Multi-engine)



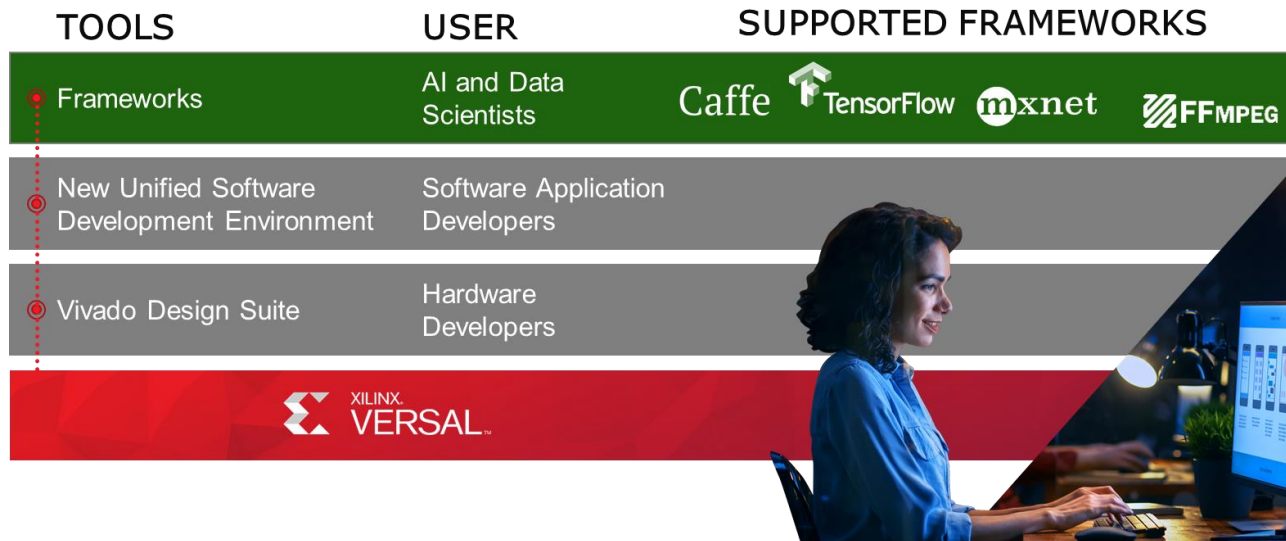
Performance-Optimized Software Libraries (Examples)



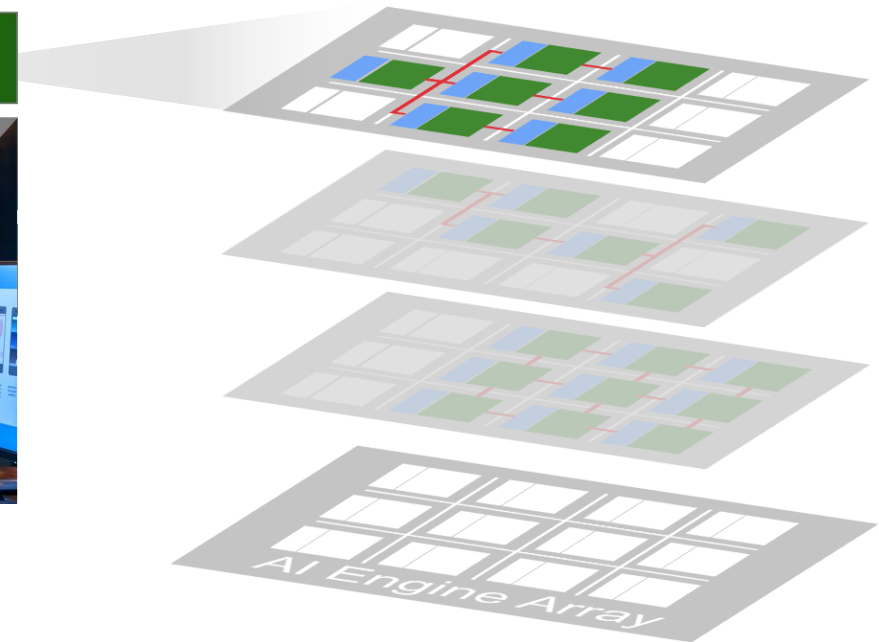
Run-Time Software (Examples)



Frameworks for Any Developer



Domain Specific
Architecture
(e.g. AI Inference)



**Architecture
Overlay**

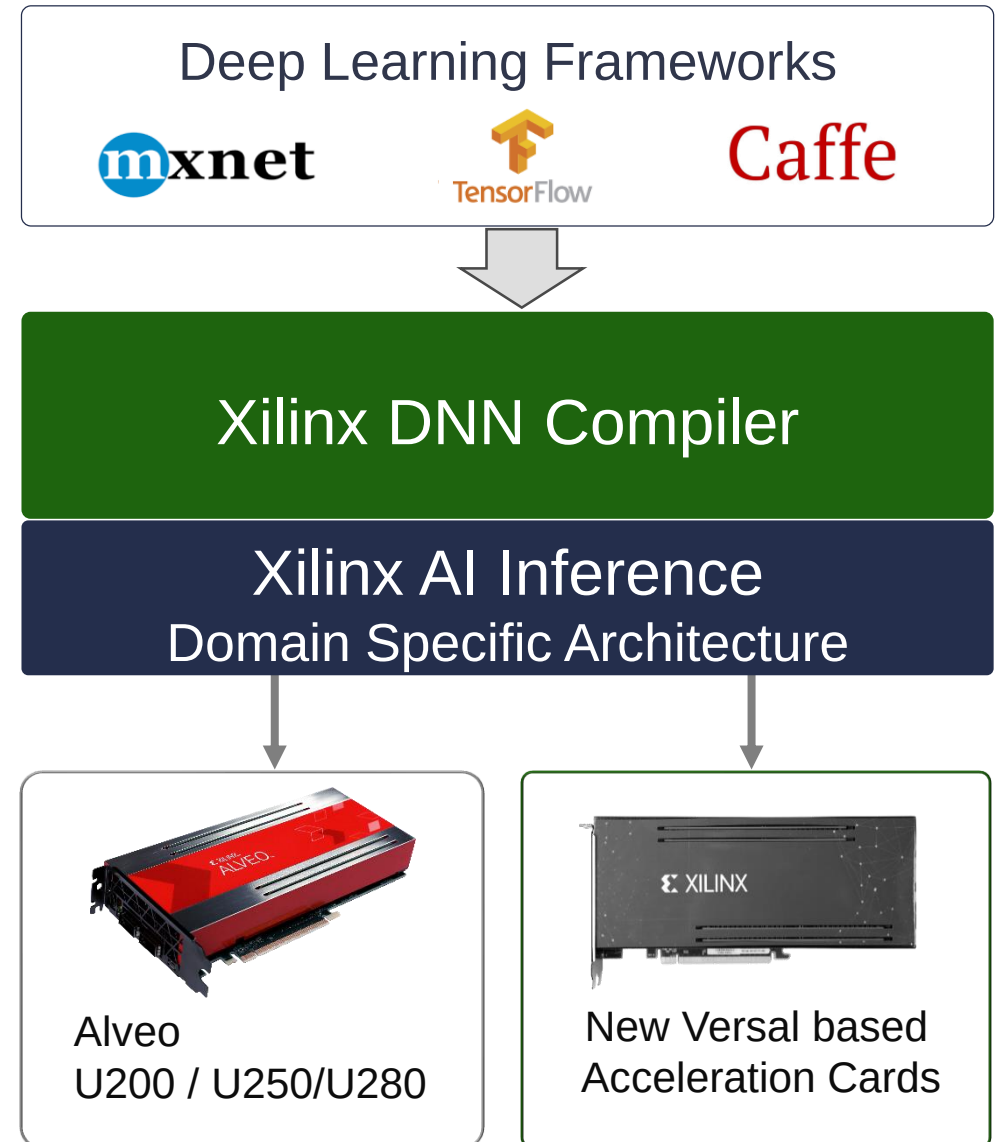
Data Flow
w/ Xilinx libraries

Kernel Program
Data Flow w/ user
defined libraries

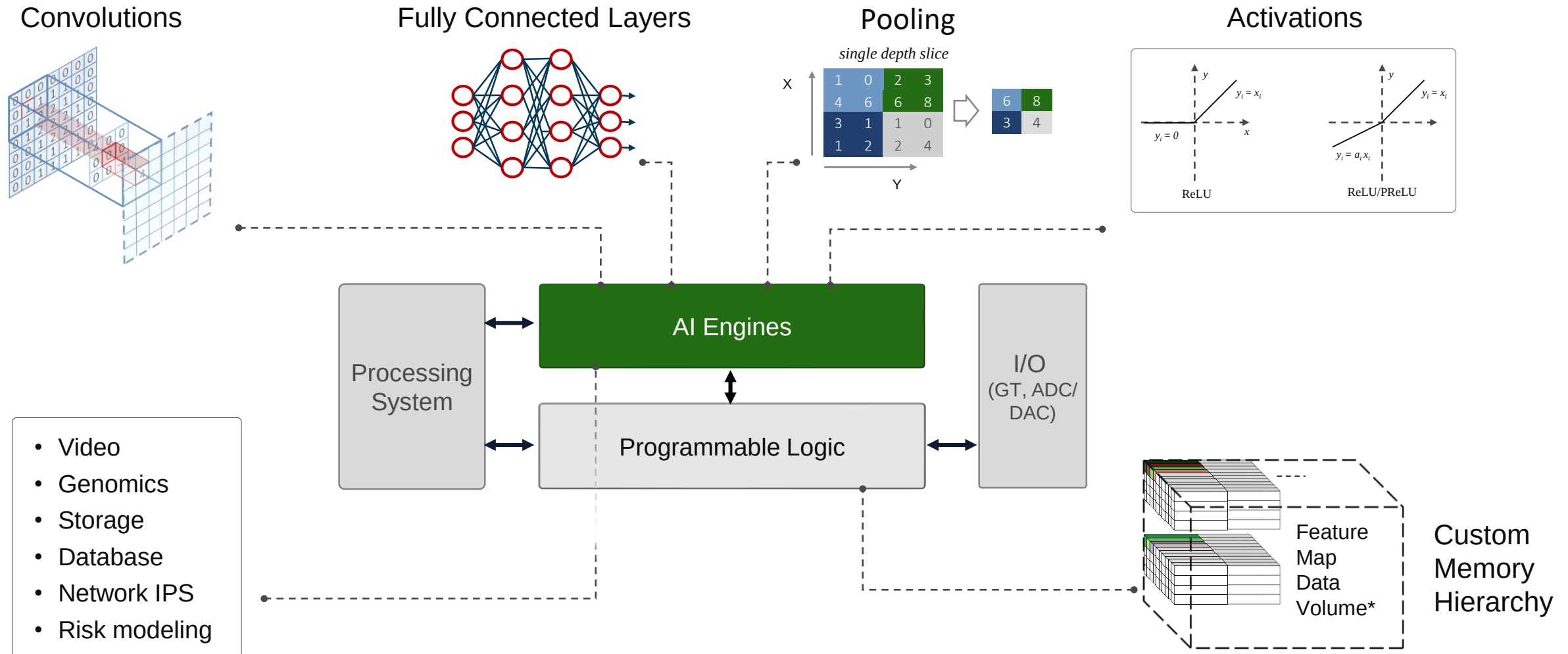
Target Domain Specific Architectures – No HW Design Experience Required

Accelerating AI Inference in the Data Center

- 1 User works in Framework of choice
 - Develop & train custom network
 - User provides trained model
- 2 Xilinx DNN Compiler implements network
 - Targets AI Inference Domain Specific Architecture
 - Quantize, merge layers, prune
 - Compile to AI Engines
- 3 Scalable across hardware targets
 - Start with Alveo today



AI Inference on Versal ACAP

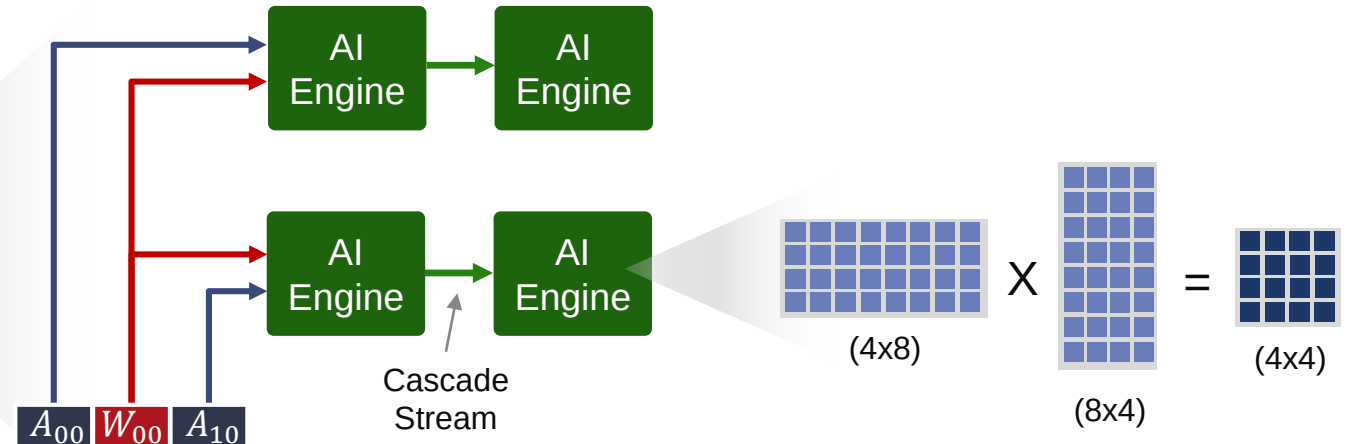
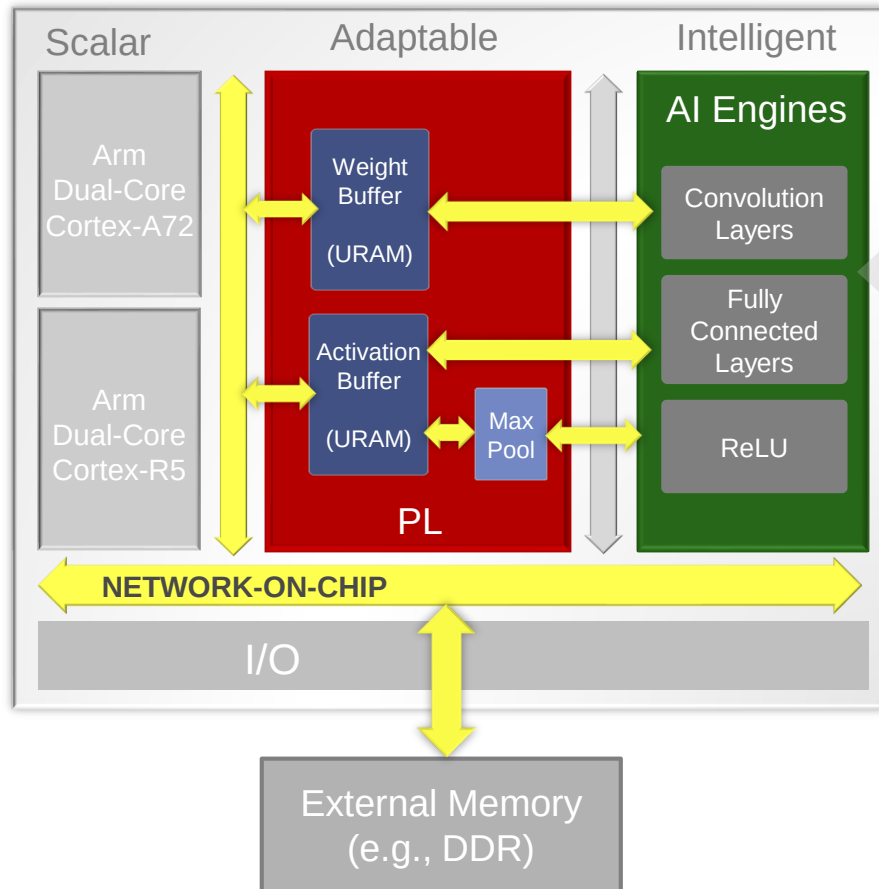


*Figure credit: https://en.wikipedia.org/wiki/Convolutional_neural_network

AI Inference Mapping on Versal ACAP

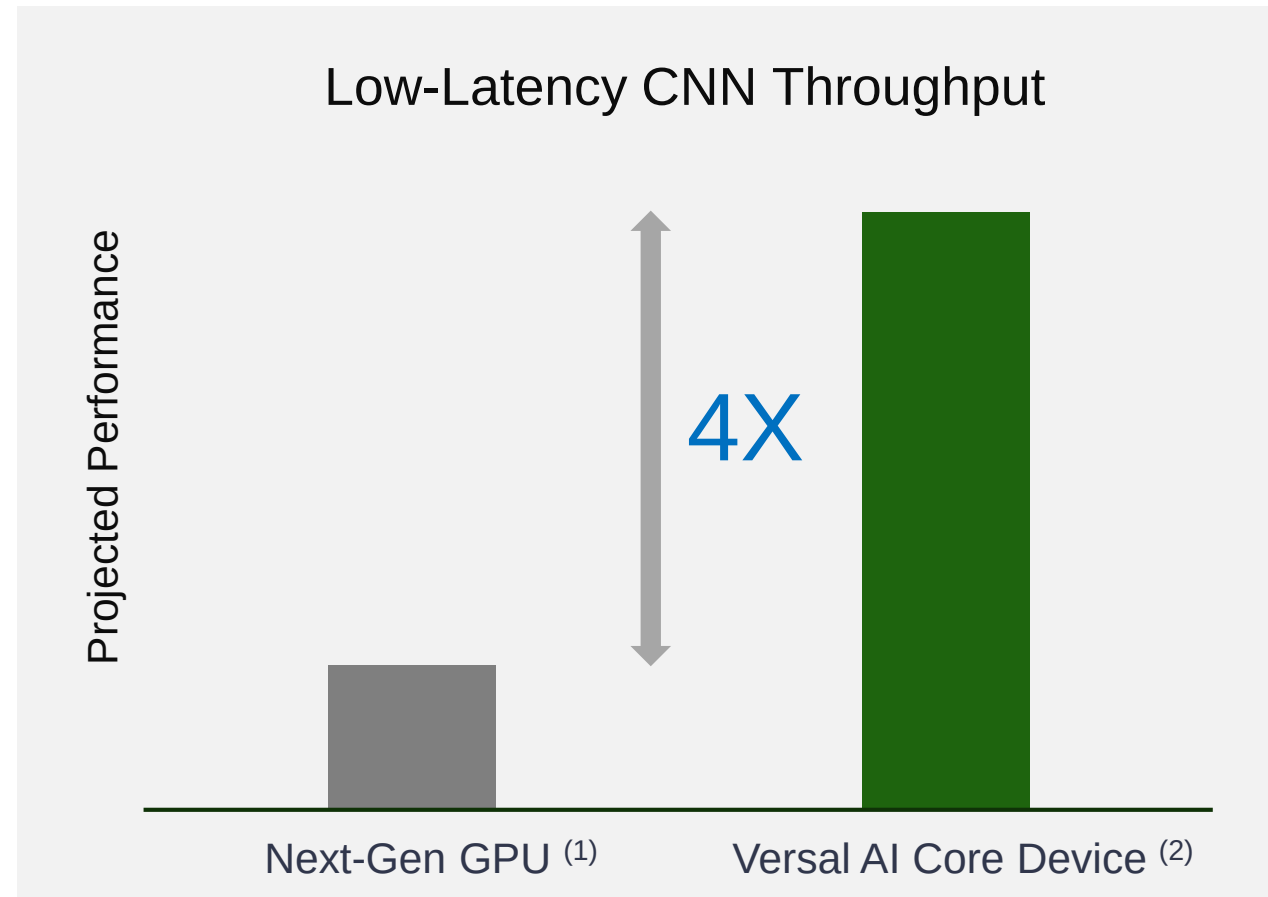
A = Activations
W = Weights

$$\begin{bmatrix} A_{00} & A_{01} \\ A_{10} & A_{11} \end{bmatrix} \times \begin{bmatrix} W_{00} & W_{01} \\ W_{10} & W_{11} \end{bmatrix} = \begin{bmatrix} A_{00} \times W_{00} + A_{01} \times W_{10} & \dots \\ A_{10} \times W_{00} + A_{11} \times W_{10} & \dots \end{bmatrix}$$



- > Custom memory hierarchy
 - > Buffer on-chip vs off-chip; Reduce latency and power
- > Stream Multi-cast on AI interconnect
 - > Weights and Activations
 - > Read once: reduce memory bandwidth
- > AI-optimized vector instructions (128 INT8 mults/cycle)

AI Engine Delivers Real-time Inference Leadership (75W Power Envelope)



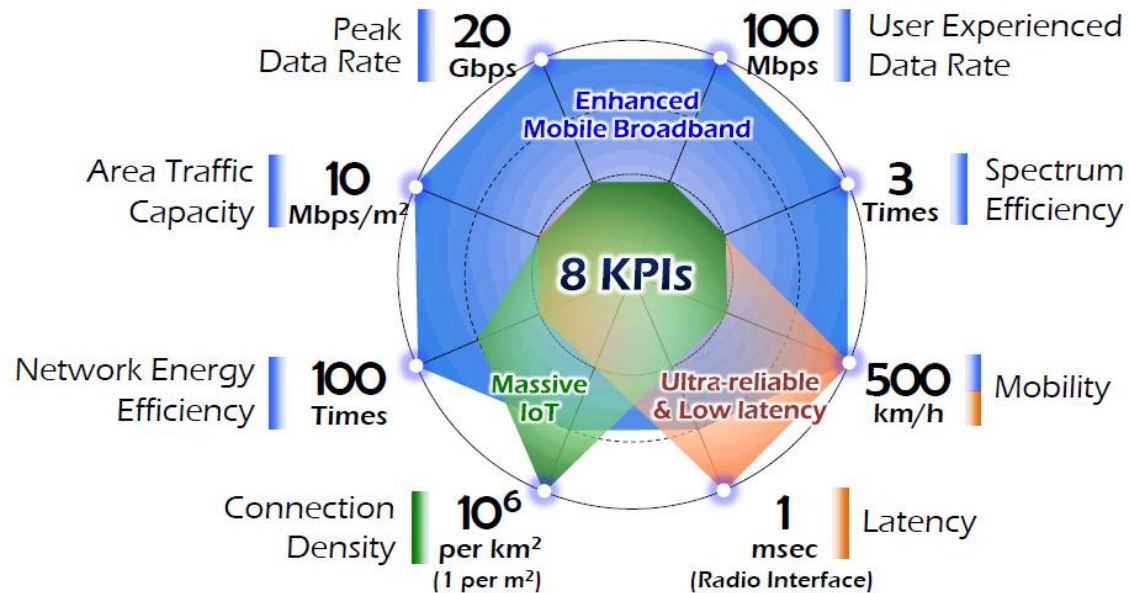
Note:
Versal device achieves 8X performance increase in 150W power envelope

(1) 12-nanometer T4 GPU device, Projected Batch=1 performance based on currently available vendor benchmarks

(2) 7-nanometer Versal AI Core Series VC1902 Device, 75W card power figures based on 2018.3 XPE power estimates, Latency <500us

Market Requirements and Trends: Wireless 5G

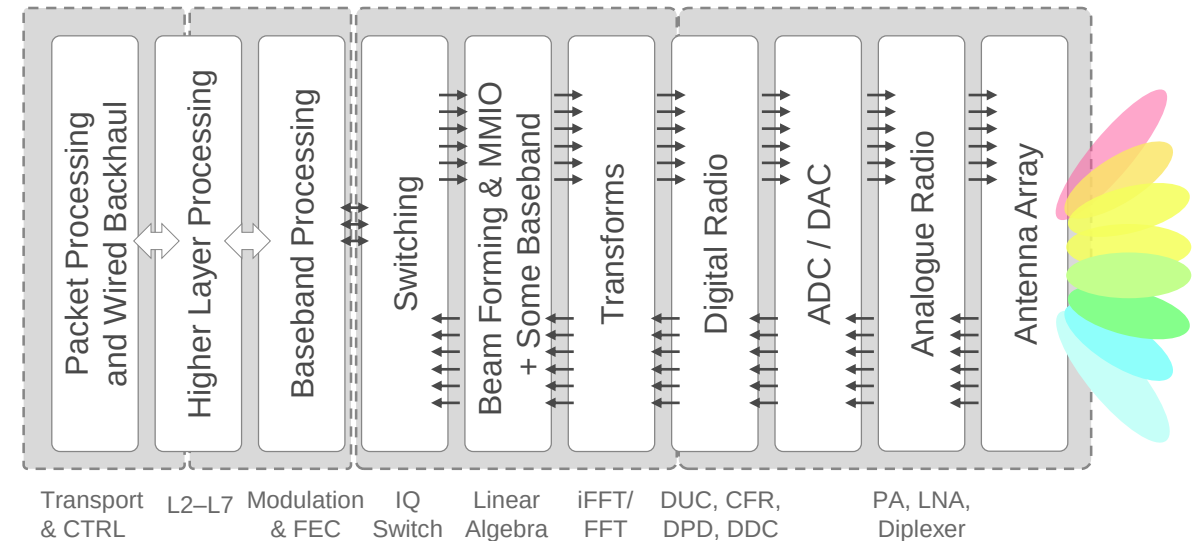
5G Complexity is 100X that of 4G *Still Evolving Standard*



ETRI RWS-150029,
5G Vision and Enabling Technologies: ETRI Perspective 3GPP RAN Workshop
Phoenix, Dec. 2015
http://www.3gpp.org/ftp/tsg_ran/TSG_RAN/TSGR_70/Docs

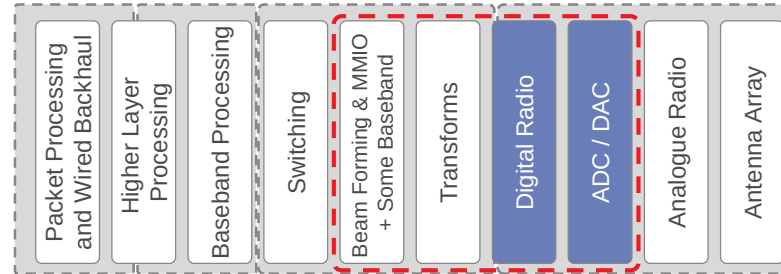
New Technologies in 5G

- > Massive MIMO
- > Multiple antenna, frequency bands
- > Changing functional partitioning



5G Wireless on Versal ACAP

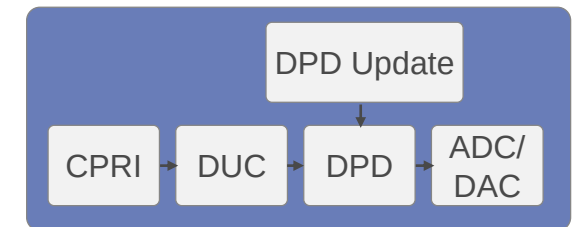
5G Wireless Infrastructure (i.e., base-station)



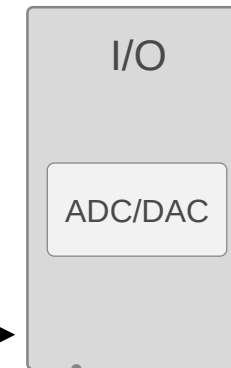
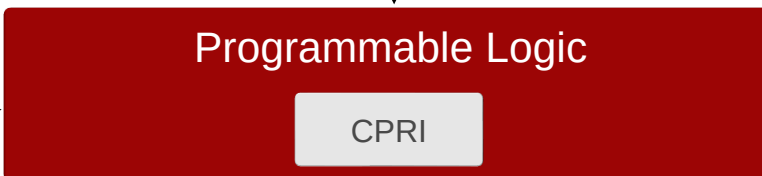
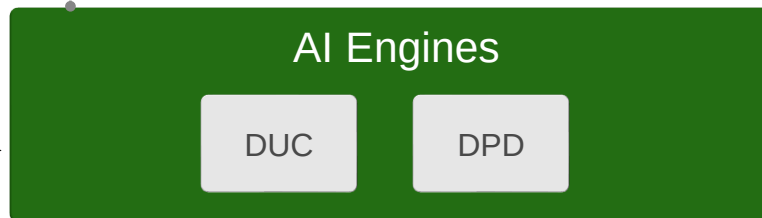
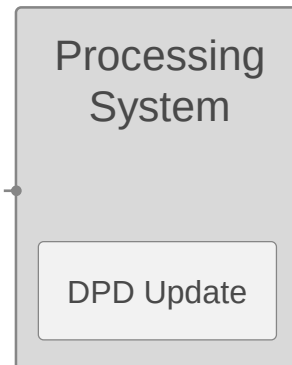
Compute Maps
to AI Engine

Mapping Example

Digital Radio
with ADC/DAC



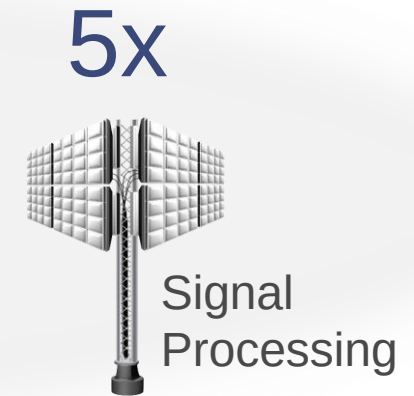
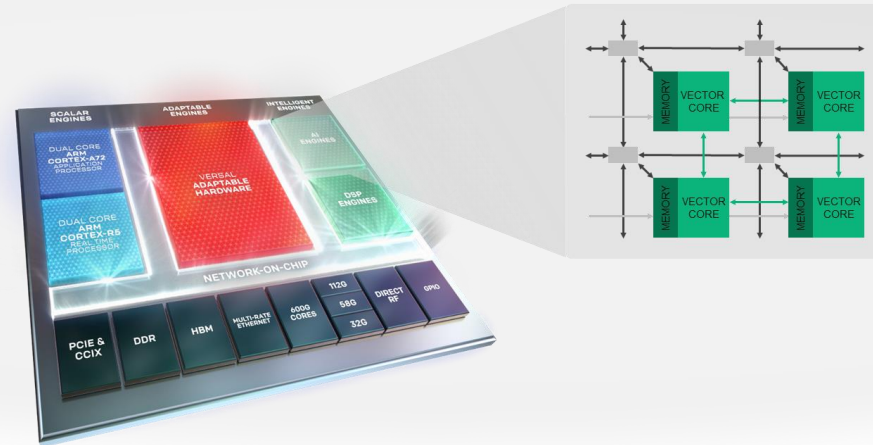
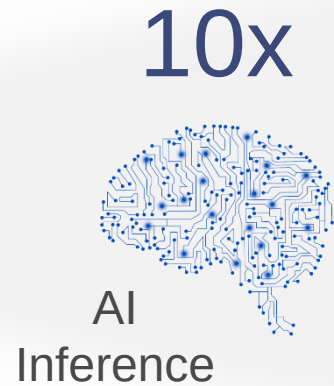
Control
Maps to PS



I/O Maps to PL

- 1: DUC: Digital Up Converter
- 2: DPD: Digital Pre-Distortion
- 3: Direct RF: ADC/DAC
- 4: CPRI: Common Public Radio Interface

AI Engine: Accelerating AI Inference & Signal Processing



Software Programmable

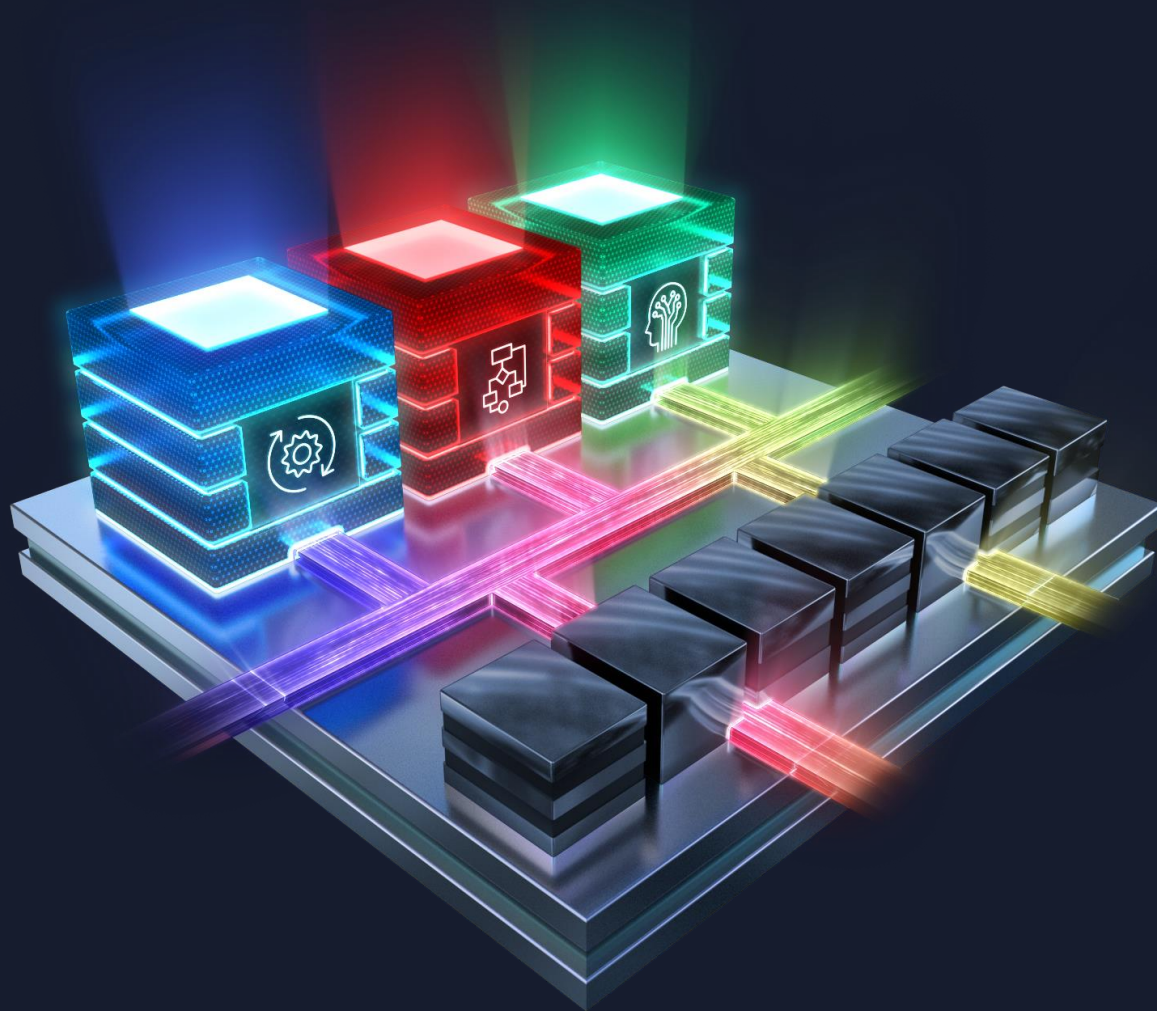
- Frameworks & C/C++
- SW Compile, Debug & Deploy

Deterministic

- Max throughput w/ low latency
- Real-time inference leadership

Efficient

- Up to 8X compute density
- At ~40% lower power



www.xilinx.com/versal

VC1902:133TOPS (int8 peak)

Versal AI Core Series — Resources

			VC1352	VC1502	VC1702	VC1802	VC1902
Intelligent Engines	AI Engines		128	217	310	300	400
	AI Engine Data Memory Blocks (#)		1024	1736	2480	2400	3200
	AI Engine Data Memory (Mb)		32	54.25	77.5	75	100
	DSP Engines		928	1,312	1,272	1,600	1,968
Adaptable Engines	System Logic Cells (K)		540	797	1,021	1,586	1,968
	LUTs		246,784	364,544	466,688	725,000	899,840
	Distributed RAM (Mb)		8	11	14	22	27
Memory	Total Block RAM (Mb)		18	19	29	28	34
	UltraRAM (Mb)		42	60	113	91	130
	Accelerator RAM (Mb)		32	0	32	0	0
	Total SRAM Capacity (Mb)		92	80	174	120	164
Scalar Engines	Application Processing Unit		Dual-core Arm® Cortex-A72, 48KB/32KB L1 Cache w/ parity & ECC; 1MB L2 Cache w/ ECC				
	Real-time Processing Unit		Dual-core Arm Cortex-R5, 32KB/32KB L1 Cache, and 256KB TCM w/ECC				
	Memory		256KB On-Chip Memory w/ECC				
	Connectivity		Ethernet (x2); UART (x2); CAN-FD (x2); USB 2.0 (x1); SPI (x2); I2C (x2)				
Foundational Platform	NoC Master / NoC Slave Ports		10	14	18	28	28
	DDR Bus Width		128	128	128	256	256
	DDR Memory Controllers		2	2	2	4	4
	CCIX & PCIe® w/DMA (CPM)		–	1 x Gen4x16, CCIX	–	1 x Gen4x16, CCIX	1 x Gen4x16, CCIX
	PCI Express®		1 x Gen4x8	4 x Gen4x8	1 x Gen4x8	4 x Gen4x8	4 x Gen4x8
	Multirate Ethernet MAC		1	4	3	4	4
	SD-FEC		2	0	5	0	0
Platform Management Controller			Boot, Security, Safety, Monitoring, and High Speed Debug				
Package Footprint	Package Dimensions	Ball Pitch	XPIO, HDIO, MIO, GTY	XPIO, HDIO, MIO, GTY	XPIO, HDIO, MIO, GTY	XPIO, HDIO, MIO, GTY	XPIO, HDIO, MIO, GTY
A1024	31x31	0.92	378, 22, 78, 8	378, 22, 78, 8			
E1369	35x35	0.92	378, 44, 78, 8		378, 44, 78, 24		
A1596	37.5x37.5	0.92		378, 44, 78, 32	378, 44, 78, 16	378, 44, 78, 32	378, 44, 78, 32
D1760	40x40	0.92					648, 44, 78, 24
A2197	45x45	0.92		378, 44, 78, 44		648, 44, 78, 44	648, 44, 78, 44

All parameters listed are maximum values. Verify all data in this document with the device data sheets or product guides found at: www.xilinx.com.

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